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PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Sayaka TSUCHIYAMA	03/28/2013
Isao ICHIKAWA	03/28/2013

RECEIVING PARTY DATA

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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13832210

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ATTORNEY DOCKET NUMBER:	919.0027
NAME OF SUBMITTER:	Warren Zitlau
Signature:	/Warren Zitlau/
Date:	07/09/2013

Total Attachments: 1
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Attorney Docket No. 919.0027

ASSIGNMENT OF PATENT APPLICATION

FOR GOOD AND VALUABLE CONSIDERATION,

I, the undersigned hereby agrees to assign for good and valuable consideration, receipt of which is hereby expressly acknowledged, and do hereby sell, assign and transfer unto

LINTEC Corporation of 23-23 Honcho, Itabashi-ku, Tokyo 173-0001, Japan

a corporation organized under the laws of JAPAN, and its successors, assigns and legal representatives, the entire right, title and interest, for all countries in and to certain inventions relating to Adhesive Composition, An Adhesive Sheet and a Production Method of a Semiconductor Device

described in an application for Letters Patent of the United States, identified as Attorney Docket No. 919.0027, at Cahn & Samuels, LLP, 1100 17th Street N.W., Suite 401, Washington, DC 20036-4650 and filed on 15 Mar, 2013, as Application Serial No. 13/832,210, and the invention(s) and improvement(s) set forth therein, and any and all continuations, continuations-in-part, divisionals, and renewals of and substitutes for said application for said Letters Patent, and all the rights and privileges under any and all Letters Patent that may be granted therefor in any country, and any reissues, or reexaminations, or extensions of said Letters Patent. I request that any and all Letters Patent for said inventions be issued to said Assignee, its successors, assigns and legal representatives, or to such nominees as it may designate.

I agree that, when requested, I will, without charge to said Assignee but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable or convenient for securing and maintaining patents for said inventions in any and all countries and for vesting title thereto in said Assignee, its successors, assigns and legal representatives or nominees.

I authorize and empower the said Assignee, its successors, assigns and legal representatives or nominees, to invoke and claim for any application for patent or other form of protection for said inventions filed by it or them, the benefit of the right of priority provided by the International Convention for the Protection of Industrial Property, as amended, or by any convention which may henceforth be substituted for it, and to invoke and claim such right of priority without further written or oral authorization from me.

I hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any assignment, consent to file or like document which may be required in any country for any purpose and more particularly in proof of the right of the said Assignee or nominee to claim the aforesaid benefit of the right of priority provided by the International convention which may henceforth be substituted for it.

I hereby authorize Warren A. Zitlau, attorney for Assignee, to insert the filing date and Serial number into the first paragraph of this assignment, after the application for Letters Patent has been filed, and the U.S. Patent Office has assigned such application a Serial Number.

I covenant with said Assignee, its successors, assigns and legal representatives, that the rights and property herein conveyed are free and clear of any encumbrance, and that I have full right to convey the same as herein expressed.

IN WITNESS WHEREOF, I have hereunto signed my name on the day and year set forth below.

Sayaka Tsuchiyama
Inventor's Signature
Sayaka TSUCHIYAMA
Inventor's Printed Name

28. Mar. 2013
DATE

Isao Ichikawa
Inventor's Signature
Isao ICHIKAWA
Inventor's Printed Name

28. Mar. 2013
DATE